



Material Content Data Sheet

Sales Product Name	TLE6710Q			Issued		28. August 2013		
MA#	MA000043164							
Package	P-MQFP-64-11			Weight*		946.40 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	27.335	2.89	2.89	28883	28883
leadframe	non noble metal	magnesium	7439-95-4	0.317	0.03		335	
	inorganic material	silicon	7440-21-3	1.375	0.15		1453	
	non noble metal	nickel	7440-02-0	6.348	0.67		6708	
	non noble metal	copper	7440-50-8	203.573	21.51	22.36	215103	223599
wire	noble metal	gold	7440-57-5	3.789	0.40	0.40	4003	4003
encapsulation	plastics	brominated resin	-	6.938	0.73		7331	
	organic material	carbon black	1333-86-4	6.938	0.73		7331	
	inorganic material	antimonytrioxide	1309-64-4	14.569	1.54		15394	
	plastics	epoxy resin	-	75.620	7.99		79903	
	inorganic material	silicondioxide	60676-86-0	589.697	62.31	73.30	623097	733056
leadfinish	non noble metal	lead	7439-92-1	0.752	0.08		795	
	non noble metal	tin	7440-31-5	2.706	0.29	0.37	2859	3654
plating	noble metal	silver	7440-22-4	1.184	0.13	0.13	1251	1251
glue	plastics	epoxy resin	-	1.051	0.11		1111	
	noble metal	silver	7440-22-4	4.205	0.44	0.55	4443	5554
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com